

Overo FE Computer-On-Module Technical Specifications



Architecture	
Product Family	Overo
Central Processing Unit	Texas Instruments OMAP3530 @ 600 MHz
Processor Architecture	ARM Cortex-A8
Digital Signal Processor	Texas Instruments C64x Fixed Point DSP @ 660 - 800 MHz
Memory	
RAM	512MB DDR SDRAM
Storage	512MB NAND Flash Memory
Graphics	
Graphics Acceleration	PowerVR SGX530 with OpenGL
Connectivity	
Camera	27-Pin Connector
Storage	microSD Card Slot
Breakout	2 × 70-Pin AVX Connectors
Power	
PMIC	Texas Instruments TPS65950
Power Input	3.3 – 4.2 V DC
Physical Specifications	
Dimensions	58mm × 17mm × 4.2mm
Weight	5.6g
Industrial Temperature Rating	–40°C – 85°C except: microSD Card Slot: –25°C – 85°C Bluetooth/WiFi Module: –20°C – 75°C PoP Memory: –25°C – 85°C
RoHS Compliant	Yes